

# MOSFET – Power, Single N-Channel, TDFNW8 60 V, 0.72 mΩ, 464 A NTMTS0D7N06C

## Features

- Small Footprint (8x8 mm) for Compact Design
- Low  $R_{DS(on)}$  to Minimize Conduction Losses
- Low  $Q_G$  and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

## Typical Applications

- Power Tools, Battery Operated Vacuums
- UAV/Drones, Material Handling
- BMS/Storage, Home Automation

## MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

| Parameter                                                                 |                                               |                        | Symbol                            | Value       | Unit |
|---------------------------------------------------------------------------|-----------------------------------------------|------------------------|-----------------------------------|-------------|------|
| Drain-to-Source Voltage                                                   |                                               |                        | V <sub>DSS</sub>                  | 60          | V    |
| Gate-to-Source Voltage                                                    |                                               |                        | V <sub>GS</sub>                   | ±20         | V    |
| Continuous Drain Current R <sub>θJC</sub> (Note 2)                        | Steady State                                  | T <sub>C</sub> = 25°C  | I <sub>D</sub>                    | 464         | A    |
|                                                                           |                                               | T <sub>C</sub> = 100°C |                                   | 328.1       |      |
| Power Dissipation R <sub>θJC</sub> (Note 2)                               |                                               | T <sub>C</sub> = 25°C  | P <sub>D</sub>                    | 294.6       | W    |
|                                                                           |                                               | T <sub>C</sub> = 100°C |                                   | 147.3       |      |
| Continuous Drain Current R <sub>θJA</sub> (Notes 1, 2)                    | Steady State                                  | T <sub>A</sub> = 25°C  | I <sub>D</sub>                    | 60.5        | A    |
|                                                                           |                                               | T <sub>A</sub> = 100°C |                                   | 42.7        |      |
| Power Dissipation R <sub>θJA</sub> (Notes 1, 2)                           |                                               | T <sub>A</sub> = 25°C  | P <sub>D</sub>                    | 5.0         | W    |
|                                                                           |                                               | T <sub>A</sub> = 100°C |                                   | 2.5         |      |
| Pulsed Drain Current                                                      | T <sub>A</sub> = 25°C, t <sub>p</sub> = 10 μs |                        | I <sub>DM</sub>                   | 900         | A    |
| Operating Junction and Storage Temperature Range                          |                                               |                        | T <sub>J</sub> , T <sub>stg</sub> | -55 to +175 | °C   |
| Source Current (Body Diode)                                               |                                               |                        | I <sub>S</sub>                    | 245.5       | A    |
| Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 40 A) |                                               |                        | E <sub>AS</sub>                   | 1754        | mJ   |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 s)         |                                               |                        | T <sub>L</sub>                    | 260         | °C   |

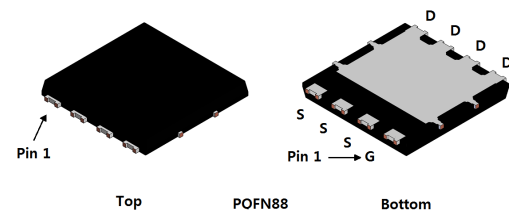
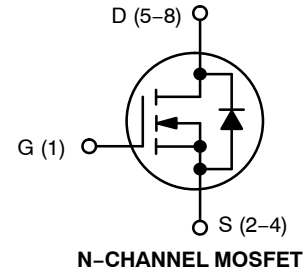
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL RESISTANCE MAXIMUM RATINGS

| Parameter                                   | Symbol          | Value | Unit               |
|---------------------------------------------|-----------------|-------|--------------------|
| Junction-to-Case – Steady State             | $R_{\theta JC}$ | 0.5   | $^\circ\text{C/W}$ |
| Junction-to-Ambient – Steady State (Note 1) | $R_{\theta JA}$ | 30    |                    |

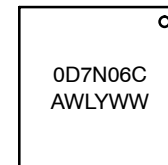
1. Surface-mounted on FR4 board using a 1 in<sup>2</sup> pad size, 2 oz. Cu pad.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

| $V_{(BR)DSS}$ | $R_{DS(ON)} \text{ MAX}$ | $I_D \text{ MAX}$ |
|---------------|--------------------------|-------------------|
| 60 V          | 0.72 mΩ @ 10 V           | 464 A             |



TDFNW8  
CASE 507AP

## MARKING DIAGRAM



A = Assembly Location  
WL = 2-digit Wafer Lot Code  
Y = Year Code  
WW = Work Week Code

## ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

# NTMTS0D7N06C

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------|--------|----------------|-----|-----|-----|------|
|-----------|--------|----------------|-----|-----|-----|------|

### OFF CHARACTERISTICS

|                                                           |                   |                                                            |                           |    |      |     |                      |
|-----------------------------------------------------------|-------------------|------------------------------------------------------------|---------------------------|----|------|-----|----------------------|
| Drain-to-Source Breakdown Voltage                         | $V_{(BR)DSS}$     | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$        |                           | 60 | –    | –   | V                    |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | $V_{(BR)DSS}/T_J$ | $I_D = 250\text{ }\mu\text{A}$ , ref to $25^\circ\text{C}$ |                           | –  | 24.7 | –   | mV/ $^\circ\text{C}$ |
| Zero Gate Voltage Drain Current                           | $I_{DSS}$         | $V_{GS} = 0\text{ V}, V_{DS} = 60\text{ V}$                | $T_J = 25^\circ\text{C}$  | –  | –    | 10  | $\mu\text{A}$        |
|                                                           |                   |                                                            | $T_J = 125^\circ\text{C}$ | –  | –    | 250 |                      |
| Gate-to-Source Leakage Current                            | $I_{GSS}$         | $V_{DS} = 0\text{ V}, V_{GS} = 20\text{ V}$                |                           | –  | –    | 100 | nA                   |

### ON CHARACTERISTICS (Note 3)

|                                            |                  |                                                            |     |       |      |                      |
|--------------------------------------------|------------------|------------------------------------------------------------|-----|-------|------|----------------------|
| Gate Threshold Voltage                     | $V_{GS(TH)}$     | $V_{GS} = V_{DS}, I_D = 250\text{ }\mu\text{A}$            | 2.0 | –     | 4.0  | V                    |
| Negative Threshold Temperature Coefficient | $V_{GS(TH)}/T_J$ | $I_D = 250\text{ }\mu\text{A}$ , ref to $25^\circ\text{C}$ | –   | –7.93 | –    | mV/ $^\circ\text{C}$ |
| Drain-to-Source On Resistance              | $R_{DS(on)}$     | $V_{GS} = 10\text{ V}, I_D = 50\text{ A}$                  | –   | 0.55  | 0.72 | m $\Omega$           |
| Forward Transconductance                   | $g_{FS}$         | $V_{DS} = 5\text{ V}, I_D = 50\text{ A}$                   | –   | 250   | –    | S                    |
| Gate Resistance                            | $R_G$            | $T_A = 25^\circ\text{C}$                                   | –   | 1.0   | –    | $\Omega$             |

### CHARGES, CAPACITANCES & GATE RESISTANCE

|                              |              |                                                                  |   |       |   |    |
|------------------------------|--------------|------------------------------------------------------------------|---|-------|---|----|
| Input Capacitance            | $C_{ISS}$    | $V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 30\text{ V}$    | – | 11535 | – | pF |
| Output Capacitance           | $C_{OSS}$    |                                                                  | – | 8010  | – |    |
| Reverse Transfer Capacitance | $C_{RSS}$    |                                                                  | – | 174   | – |    |
| Threshold Gate Charge        | $Q_{G(TH)}$  | $V_{GS} = 10\text{ V}, V_{DS} = 30\text{ V}; I_D = 50\text{ A}$  | – | 25.7  | – | nC |
| Gate-to-Source Charge        | $Q_{GS}$     |                                                                  | – | 40.0  | – |    |
| Gate-to-Drain Charge         | $Q_{GD}$     |                                                                  | – | 20.7  | – |    |
| Total Gate Charge            | $Q_{G(TOT)}$ |                                                                  | – | 152   | – |    |
| Voltage Plateau              | $V_{GP}$     |                                                                  | – | 3.71  | – | V  |
| Total Gate Charge            | $Q_{G(TOT)}$ | $V_{GS} = 4.5\text{ V}, V_{DS} = 30\text{ V}; I_D = 50\text{ A}$ | – | 72    | – | nC |

### SWITCHING CHARACTERISTICS (Note 4)

|                     |              |                                                                                        |   |      |   |    |
|---------------------|--------------|----------------------------------------------------------------------------------------|---|------|---|----|
| Turn-On Delay Time  | $t_{d(ON)}$  | $V_{GS} = 10\text{ V}, V_{DS} = 30\text{ V}, I_D = 50\text{ A}, R_G = 6\text{ }\Omega$ | – | 39.7 | – | ns |
| Rise Time           | $t_r$        |                                                                                        | – | 29.3 | – |    |
| Turn-Off Delay Time | $t_{d(OFF)}$ |                                                                                        | – | 127  | – |    |
| Fall Time           | $t_f$        |                                                                                        | – | 42.6 | – |    |

### DRAIN-SOURCE DIODE CHARACTERISTICS

|                         |                 |                                                                                 |                        |   |      |     |    |
|-------------------------|-----------------|---------------------------------------------------------------------------------|------------------------|---|------|-----|----|
| Forward Diode Voltage   | V <sub>SD</sub> | V <sub>GS</sub> = 0 V,<br>I <sub>S</sub> = 50 A                                 | T <sub>J</sub> = 25°C  | – | 0.72 | 1.2 | V  |
|                         |                 |                                                                                 | T <sub>J</sub> = 125°C | – | 0.59 | –   |    |
| Reverse Recovery Time   | t <sub>RR</sub> | V <sub>GS</sub> = 0 V, dI <sub>S</sub> /dt = 100 A/μs,<br>I <sub>S</sub> = 50 A |                        | – | 120  | –   | ns |
| Charge Time             | t <sub>a</sub>  |                                                                                 |                        | – | 60   | –   |    |
| Discharge Time          | t <sub>b</sub>  |                                                                                 |                        | – | 60   | –   |    |
| Reverse Recovery Charge | Q <sub>RR</sub> |                                                                                 |                        | – | 324  | –   | nC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

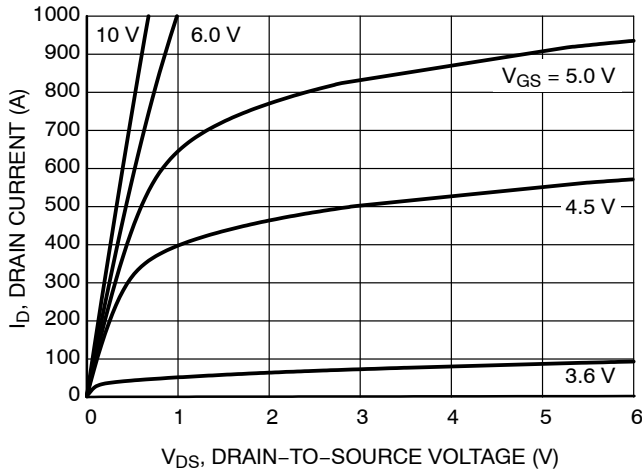


Figure 1. On-Region Characteristics

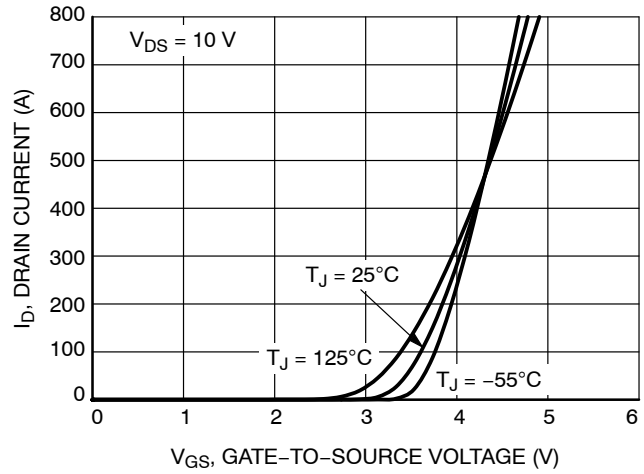


Figure 2. Transfer Characteristics

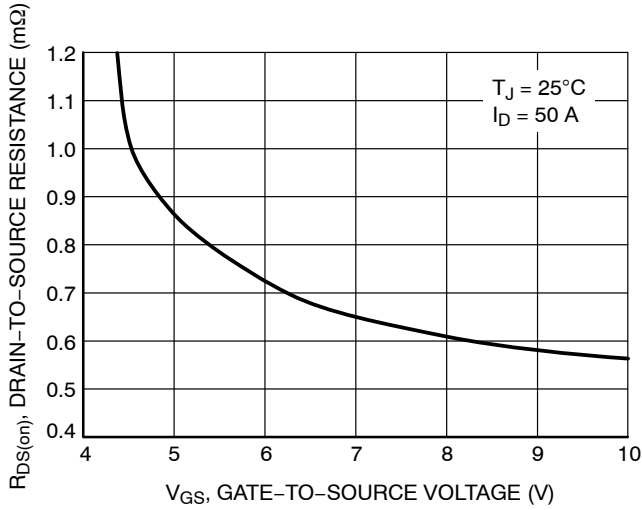


Figure 3. On-Resistance vs. Gate-to-Source Voltage

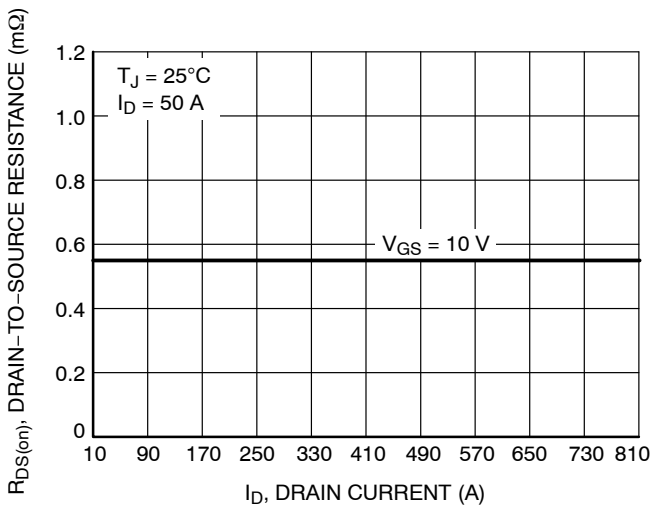


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

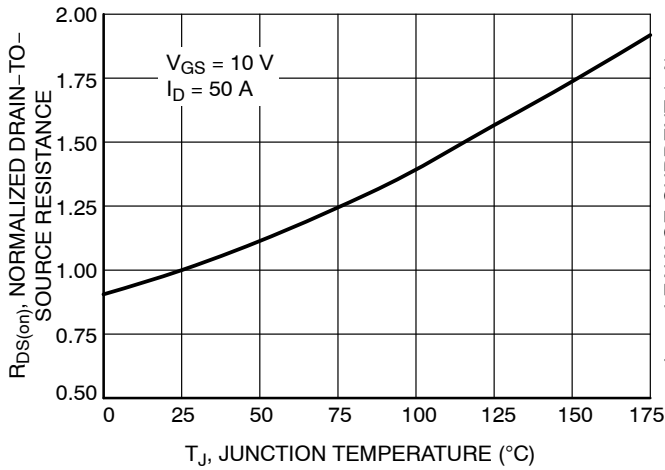


Figure 5. On-Resistance Variation with Temperature

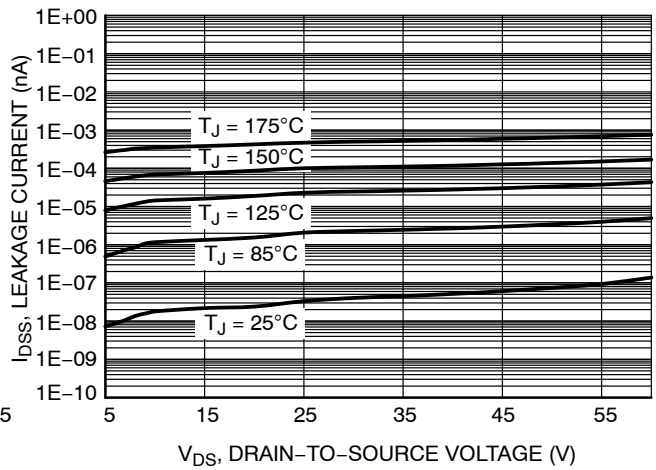


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

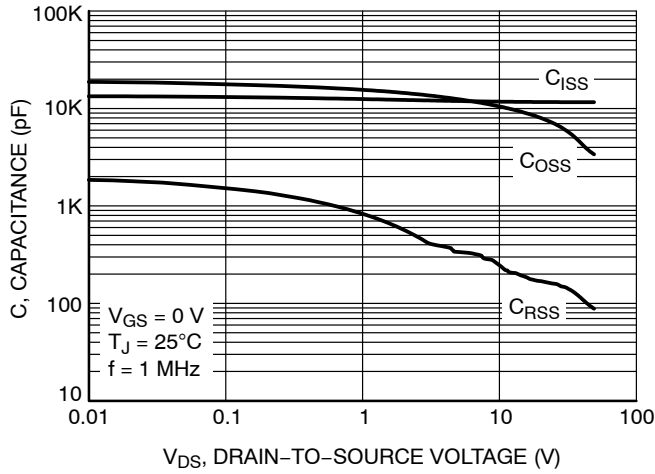


Figure 7. Capacitance Variation

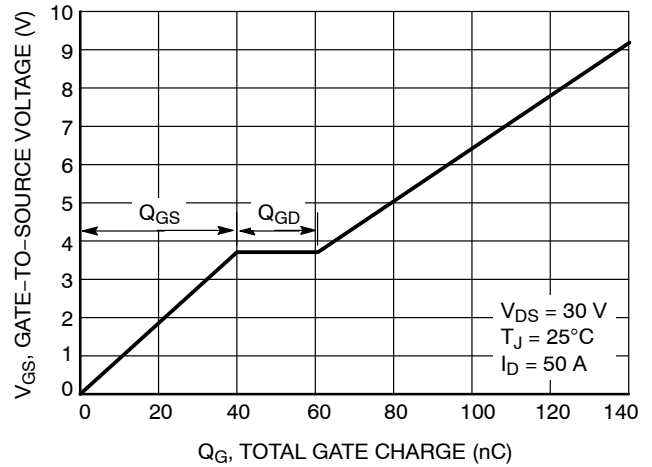


Figure 8. Gate-to-Source Voltage vs. Total Charge

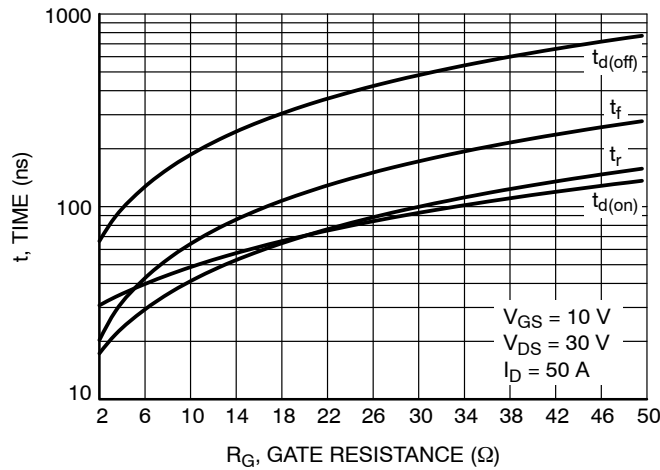


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

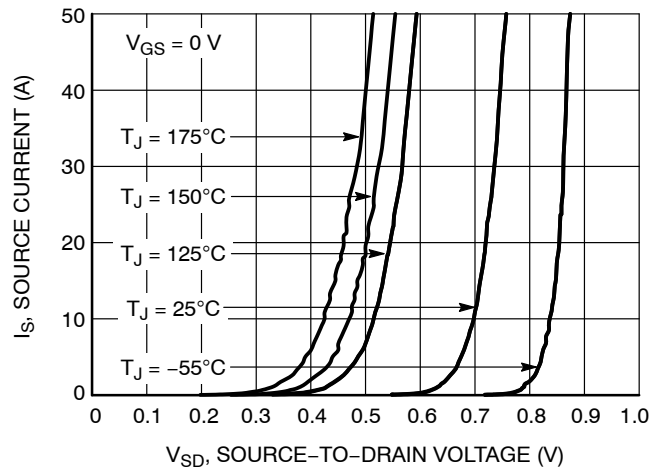


Figure 10. Diode Forward Voltage vs. Current

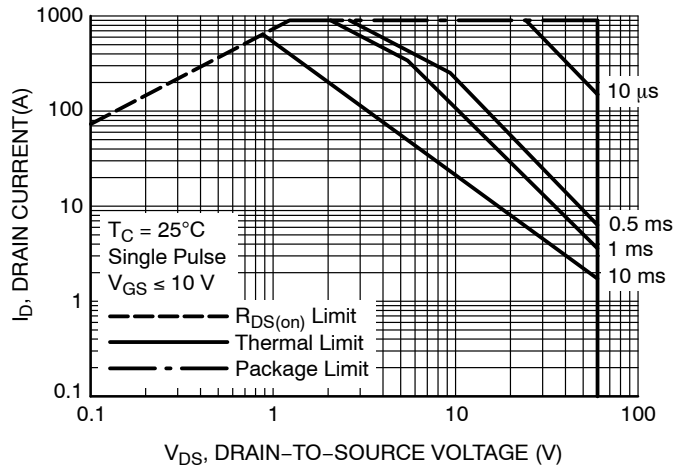


Figure 11. Maximum Rated Forward Biased Safe Operating Area

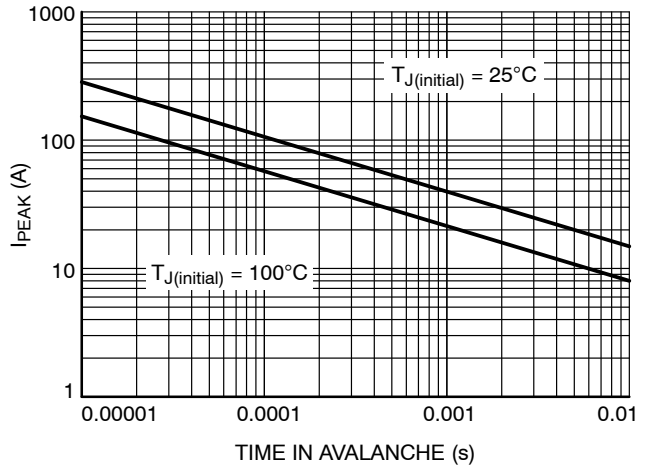


Figure 12. Maximum Drain Current vs. Time in Avalanche

# NTMTS0D7N06C

## TYPICAL CHARACTERISTICS

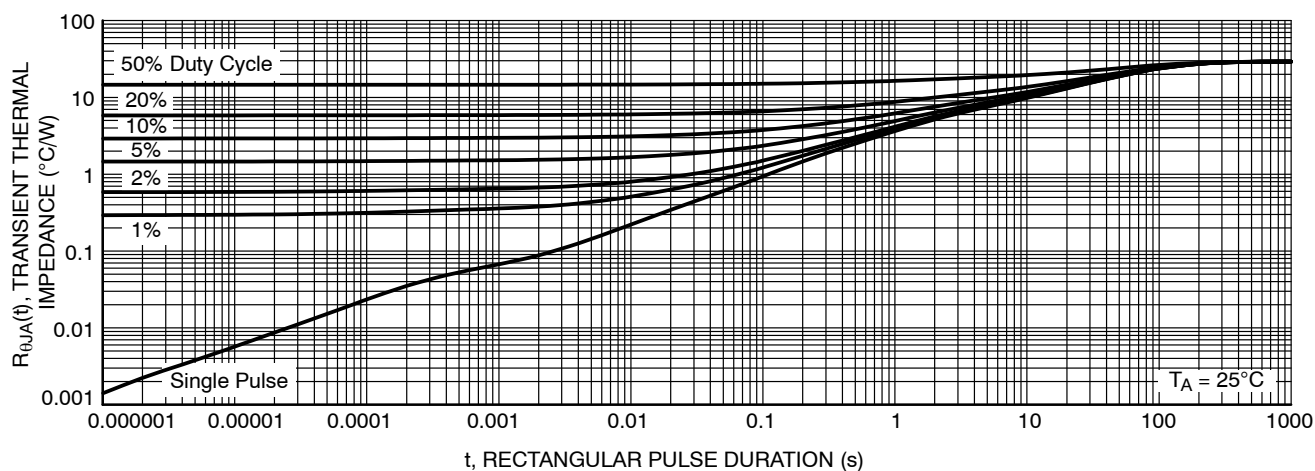


Figure 13. Thermal Response

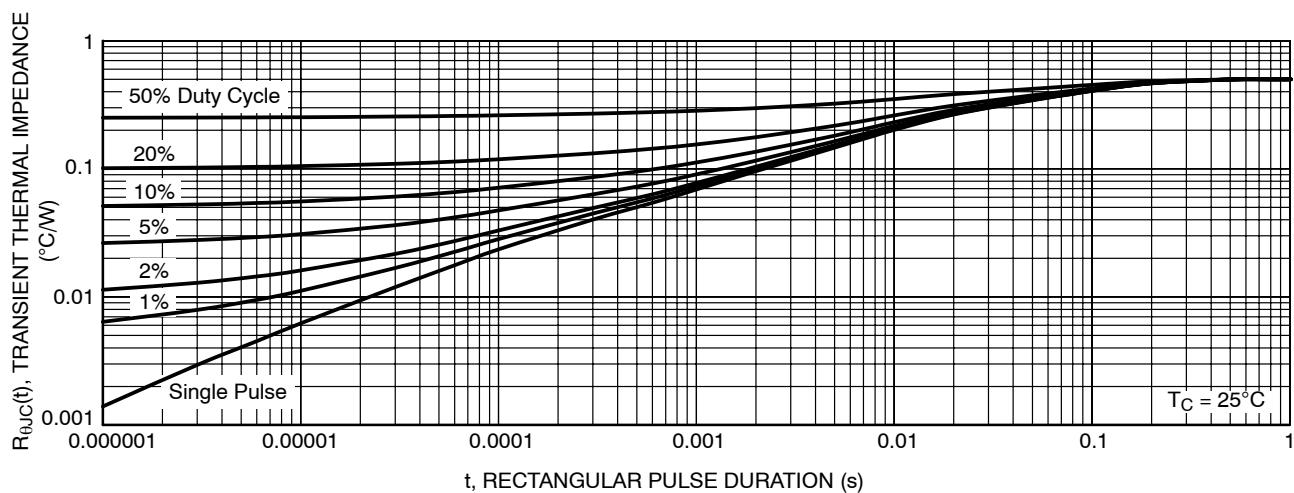


Figure 14. Thermal Response

### DEVICE ORDERING INFORMATION

| Device          | Marking | Package             | Shipping <sup>†</sup> |
|-----------------|---------|---------------------|-----------------------|
| NTMTS0D7N06CTXG | 0D7N06C | TDFNW8<br>(Pb-Free) | 3,000 / Tape & Reel   |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.


**TDFNW8 8.30x8.40x1.10, 2.00P**  
**CASE 507AP**  
**ISSUE E**

DATE 08 MAY 2024



\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



| DIM  | MILLIMETERS |      |      |
|------|-------------|------|------|
|      | MIN.        | NOM. | MAX. |
| A    | 1.00        | 1.10 | 1.20 |
| A1   | 0.00        | —    | 0.05 |
| b    | 0.90        | 1.00 | 1.10 |
| b1   | 0.35        | 0.45 | 0.55 |
| c    | 0.23        | 0.28 | 0.33 |
| D    | 8.20        | 8.30 | 8.40 |
| D1   | 7.90        | 8.00 | 8.10 |
| D2   | 6.80        | 6.90 | 7.00 |
| D3   | 6.90        | 7.00 | 7.10 |
| E    | 8.30        | 8.40 | 8.50 |
| E1   | 7.80        | 7.90 | 8.00 |
| E2   | 5.24        | 5.34 | 5.44 |
| E3   | 0.25        | 0.35 | 0.45 |
| e    | 2.00 BSC    |      |      |
| e/2  | 1.00 BSC    |      |      |
| e1   | 2.70 BSC    |      |      |
| e1/2 | 1.35 BSC    |      |      |
| K    | 1.50        | 1.57 | 1.70 |
| L    | 0.64        | 0.74 | 0.84 |
| L1   | 0.67        | 0.77 | 0.87 |
| Θ    | 0°          | —    | 12°  |

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TDFNW8 8.30x8.40x1.10, 2.00P  
CASE 507AP  
ISSUE E

DATE 08 MAY 2024

GENERIC  
MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot Code  
Y = Year Code  
WW = Work Week Code

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

|                  |                              |                                                                                                                                                                                     |
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